

## 1. General description

Hyperfast power diode in a 2-lead TO247 plastic package



## 2. Features and benefits

- Low leakage current
- Low thermal resistance
- Low reverse recovery current
- Reduces switching losses in associated MOSFET or IGBT

## 3. Applications

- LLC & PFC in EV charger
- MPPT in PV
- NPC-I in UPS
- Continuous Current Mode (CCM) Power Factor Correction (PFC)
- 2<sup>nd</sup> rectification in HB/FB SMPS

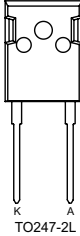
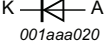
## 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Notes	Values			Unit
<b>Absolute maximum rating</b>							
$V_{RRM}$	repetitive peak reverse voltage				600		V
$I_{F(AV)}$	average forward current	$\delta = 0.5$ ; $T_{mb} \leq 92\text{ °C}$ ; square-wave pulse; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>			100		A
$I_{FRM}$	repetitive peak forward current	$\delta = 0.5$ ; $t_p = 25\ \mu\text{s}$ ; $T_{mb} \leq 92\text{ °C}$ ; square-wave pulse			200		A
$I_{FSM}$	non-repetitive peak forward current	$t_p = 10\text{ ms}$ ; $T_{j(\text{init})} = 25\text{ °C}$ ; sine-wave pulse; <a href="#">Fig. 4</a>			700		A
		$t_p = 8.3\text{ ms}$ ; $T_{j(\text{init})} = 25\text{ °C}$ ; sine-wave pulse			770		A
Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
<b>Static characteristics</b>							
$V_F$	forward voltage	$I_F = 100\text{ A}$ ; $T_j = 25\text{ °C}$ ; <a href="#">Fig. 6</a>		-	1.60	2.20	V
		$I_F = 100\text{ A}$ ; $T_j = 150\text{ °C}$ ; <a href="#">Fig. 6</a>		-	1.20	1.80	V
<b>Dynamic characteristics</b>							
$t_{rr}$	reverse recovery time	$I_F = 1\text{ A}$ ; $V_R = 30\text{ V}$ ; $dI_F/dt = 200\text{ A}/\mu\text{s}$ ; $T_j = 25\text{ °C}$ ; <a href="#">Fig. 7</a>		-	30	-	ns

## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode	 <p style="text-align: center;">K A TO247-2L</p>	 <p style="text-align: center;">K — &lt;— A 001aaa020</p>
2	A	anode		
mb	mb	mounting base; connected to cathode		

## 6. Ordering information

Table 3. Ordering information

Type number	Package Name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
BYC100MW-600PT2	TO247-2L	BYC100MW-600PT2Q	Tube	30	TO247L-2L	10-Nov-2020

## 7. Marking

Table 4. Marking codes

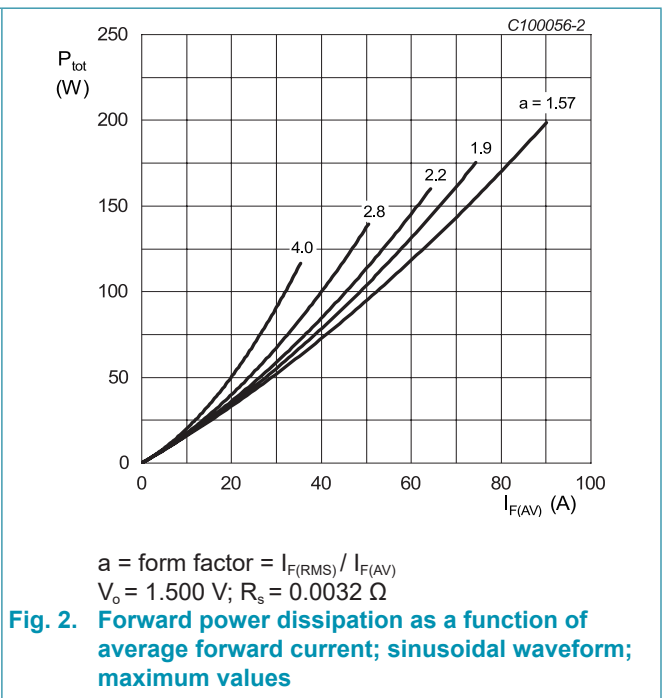
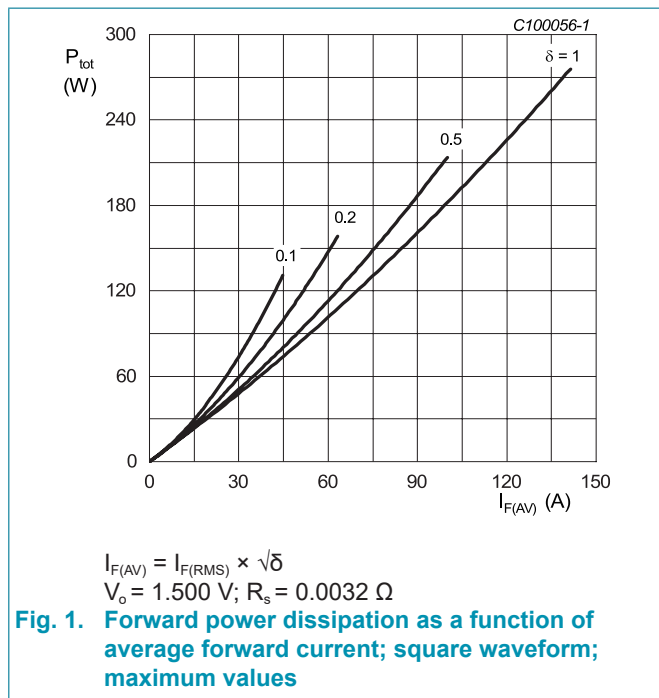
Type number	Marking codes
BYC100MW-600PT2	BYC100MW 600PT2

## 8. Limiting values

**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Notes	Values	Unit
$V_{RRM}$	repetitive peak reverse voltage			600	V
$V_{RWM}$	crest working reverse voltage			600	V
$V_R$	reverse voltage	DC		600	V
$I_{F(AV)}$	average forward current	$\delta = 0.5$ ; $T_{mb} \leq 92\text{ }^\circ\text{C}$ ; square-wave pulse; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>		100	A
$I_{FRM}$	repetitive peak forward current	$\delta = 0.5$ ; $t_p = 25\text{ }\mu\text{s}$ ; $T_{mb} \leq 92\text{ }^\circ\text{C}$ ; square-wave pulse		200	A
$I_{FSM}$	non-repetitive peak forward current	$t_p = 10\text{ ms}$ ; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$ ; sine-wave pulse; <a href="#">Fig. 4</a>		700	A
		$t_p = 8.3\text{ ms}$ ; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$ ; sine-wave pulse		770	A
$I^2t$	$I^2t$ for fusing	$t_p = 10\text{ ms}$ ; sine-wave pulse		2450	$\text{A}^2\text{s}$
$T_{stg}$	storage temperature			-65 to 175	$^\circ\text{C}$
$T_j$	junction temperature			-65 to 175	$^\circ\text{C}$



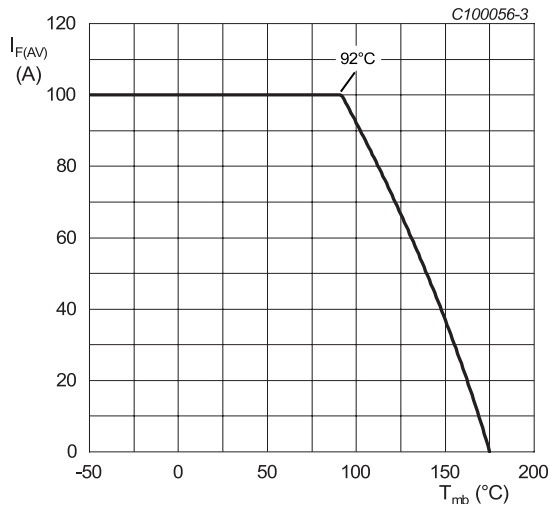


Fig. 3. Average forward current as a function of mounting base temperature; maximum values

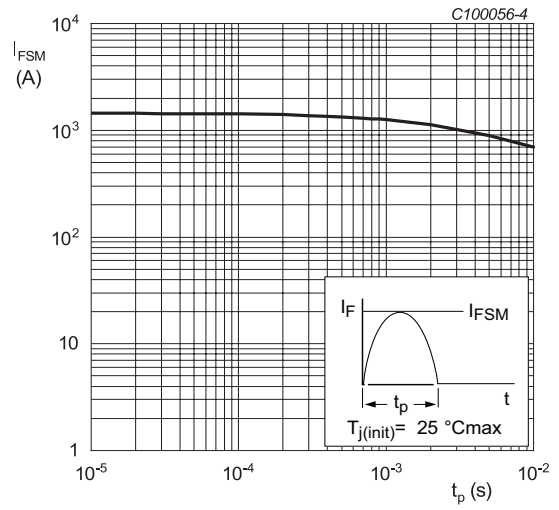


Fig. 4. Non-repetitive peak forward current as a function of pulse width; sinusoidal waveform; maximum values

### 9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	<a href="#">Fig. 5</a>		-	-	0.39	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	in free air		-	45	-	K/W

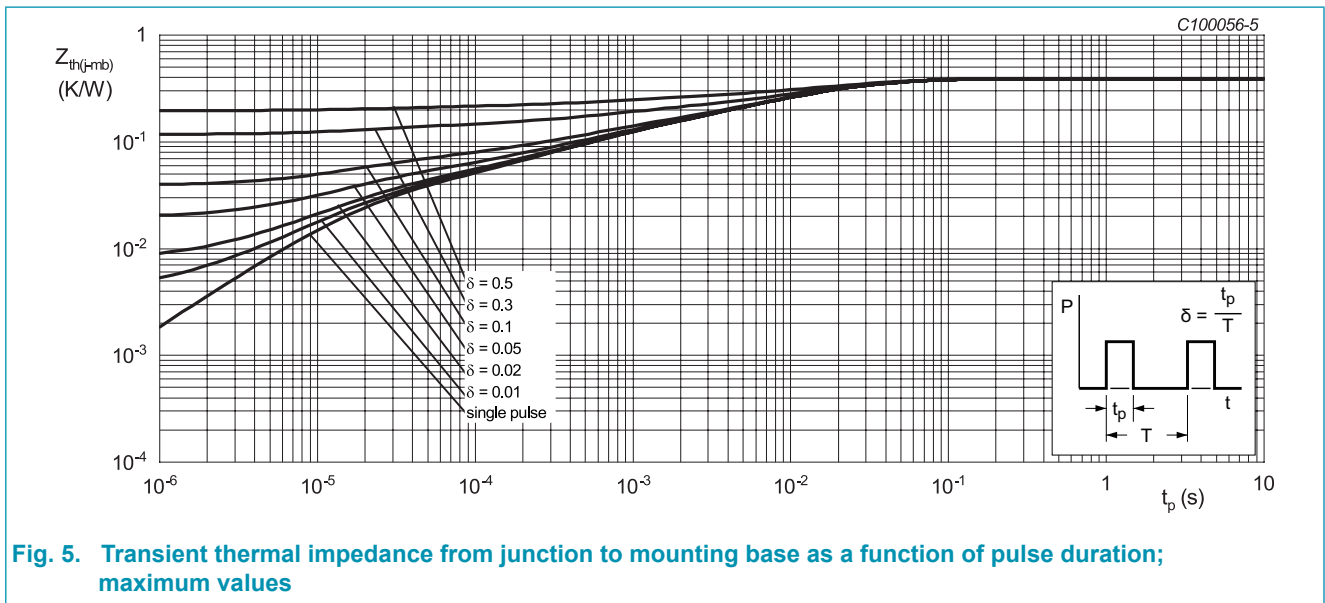
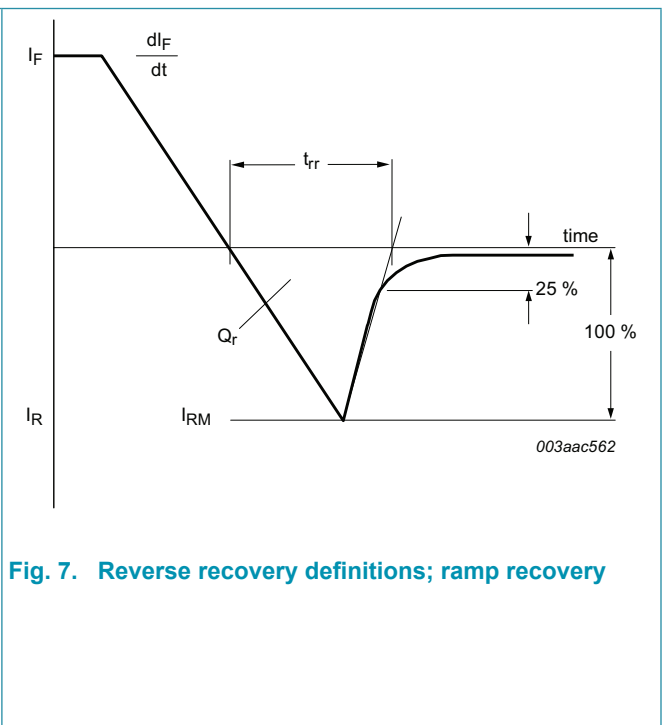
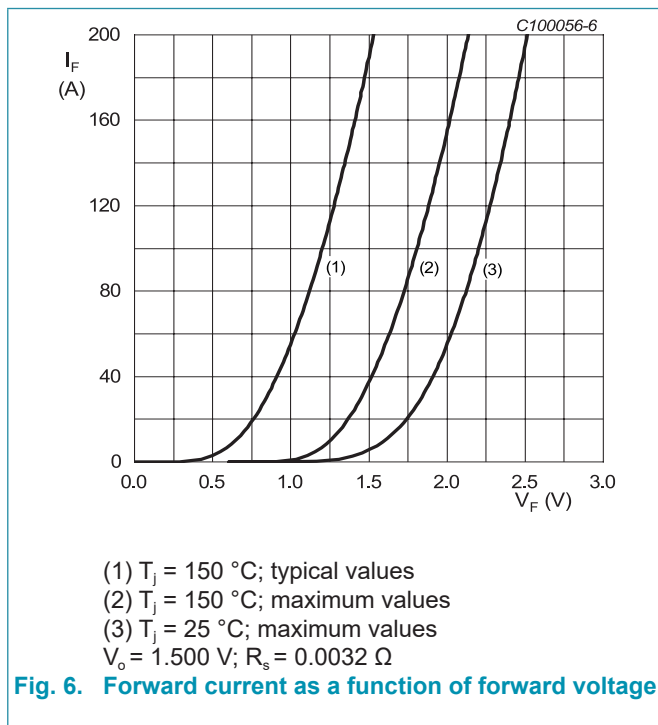


Fig. 5. Transient thermal impedance from junction to mounting base as a function of pulse duration; maximum values

### 10. Characteristics

Table 7. Characteristics

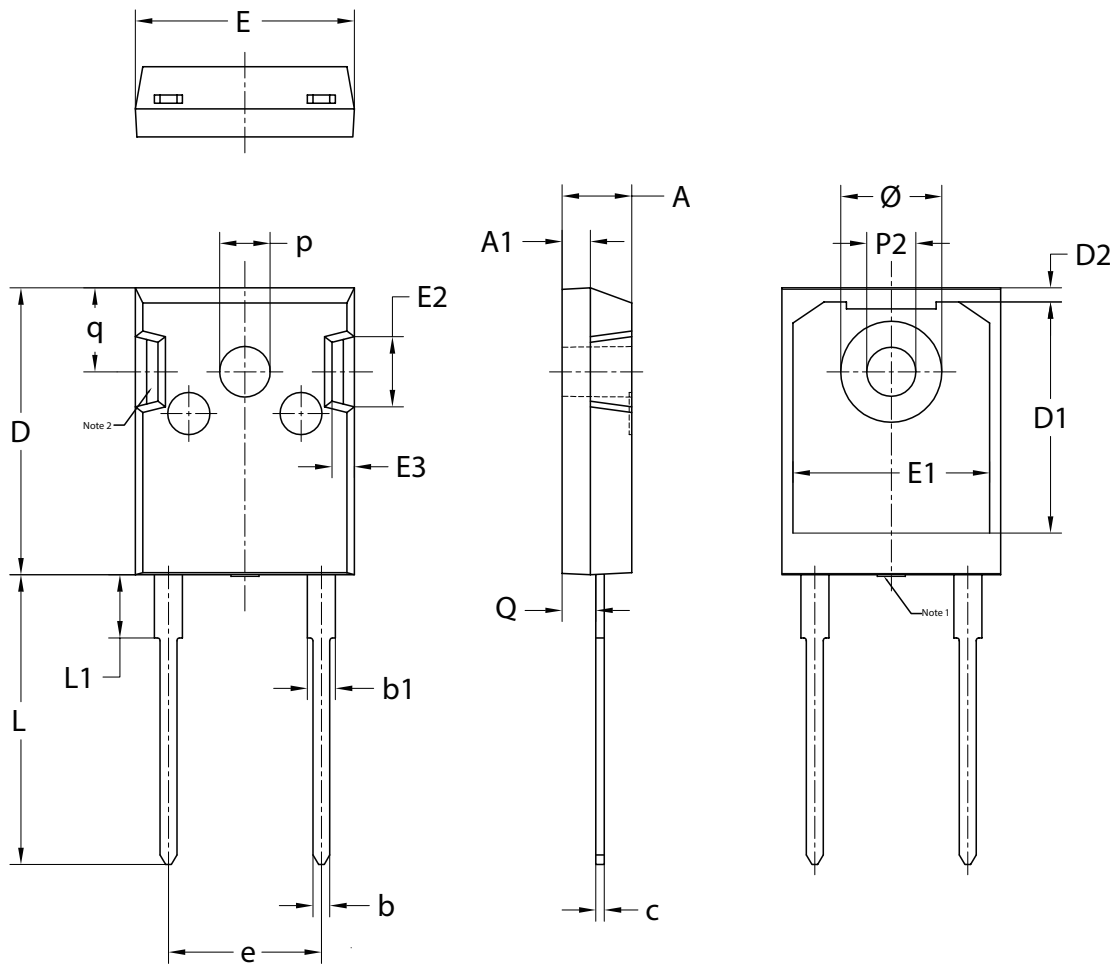
Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
<b>Static characteristics</b>							
$V_F$	forward voltage	$I_F = 100\text{ A}; T_j = 25\text{ °C}; \text{Fig. 6}$		-	1.60	2.20	V
		$I_F = 100\text{ A}; T_j = 150\text{ °C}; \text{Fig. 6}$		-	1.20	1.80	V
$I_R$	reverse current	$V_R = 600\text{ V}; T_j = 25\text{ °C}$		-	3	200	$\mu\text{A}$
		$V_R = 600\text{ V}; T_j = 150\text{ °C}$		-	0.4	5	mA
<b>Dynamic characteristics</b>							
$t_{rr}$	reverse recovery time	$I_F = 1\text{ A}; V_R = 30\text{ V}; dI_F/dt = 200\text{ A}/\mu\text{s}; T_j = 25\text{ °C}; \text{Fig. 7}$		-	30	-	ns
		$I_F = 50\text{ A}; V_R = 400\text{ V}; dI_F/dt = 200\text{ A}/\mu\text{s}; T_j = 25\text{ °C}; \text{Fig. 7}$		-	55	-	ns
		$I_F = 50\text{ A}; V_R = 400\text{ V}; dI_F/dt = 200\text{ A}/\mu\text{s}; T_j = 125\text{ °C}; \text{Fig. 7}$		-	100	-	ns
$I_{RM}$	peak reverse recovery current	$I_F = 50\text{ A}; V_R = 400\text{ V}; dI_F/dt = 200\text{ A}/\mu\text{s}; T_j = 25\text{ °C}; \text{Fig. 7}$		-	5	-	A
		$I_F = 50\text{ A}; V_R = 400\text{ V}; dI_F/dt = 200\text{ A}/\mu\text{s}; T_j = 125\text{ °C}; \text{Fig. 7}$		-	15	-	A
$Q_f$	recovered charge	$I_F = 50\text{ A}; V_R = 400\text{ V}; dI_F/dt = 200\text{ A}/\mu\text{s}; T_j = 25\text{ °C}; \text{Fig. 7}$		-	145	-	nC
		$I_F = 50\text{ A}; V_R = 400\text{ V}; dI_F/dt = 200\text{ A}/\mu\text{s}; T_j = 125\text{ °C}; \text{Fig. 7}$		-	735	-	nC
$E_{as}$	non-repetitive avalanche energy	$T_j = 25\text{ °C}$		90	-	-	mJ



### 11. Package outline

Plastic single-ended through-hole package; heatsink mounted; 1 mounting hole; 2 leads TO-247

TO247-2L



UNIT	A	A <sub>1</sub>	b	b <sub>1</sub>	c	D	D <sub>1</sub>	D <sub>2</sub>	E	E <sub>1</sub>	E <sub>2</sub>	E <sub>3</sub>	e	L	L <sub>1</sub>	P <sub>2</sub>	p	Q	q	Ø
mm	5.20	2.10	1.40	2.20	0.70	20.60	16.20	1.20	15.75	14.22	5.20	1.80	10.90	20.72	4.75	3.60	3.70	2.60	6.18	7.30
	4.70	1.90	1.00	1.80	0.50	20.30	16.87	0.80	15.45	13.82	4.80	1.40	BSC	20.22	4.25	3.40	3.50	2.20	5.78	7.10

Note:

1. Mold resin protrusion max 0.127mm.
2. Metal exposed with Sn plating.

## 12. Legal information

### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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## 13. Contents

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1. General description.....	1
2. Features and benefits .....	1
3. Applications .....	1
4. Quick reference data.....	1
5. Pinning information.....	2
6. Ordering information.....	2
7. Marking codes .....	2
8. Limiting values .....	3
9. Thermal characteristics .....	5
10. Characteristics.....	6
11. Package outline .....	7
12. Legal information .....	9
13. Contents .....	11

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